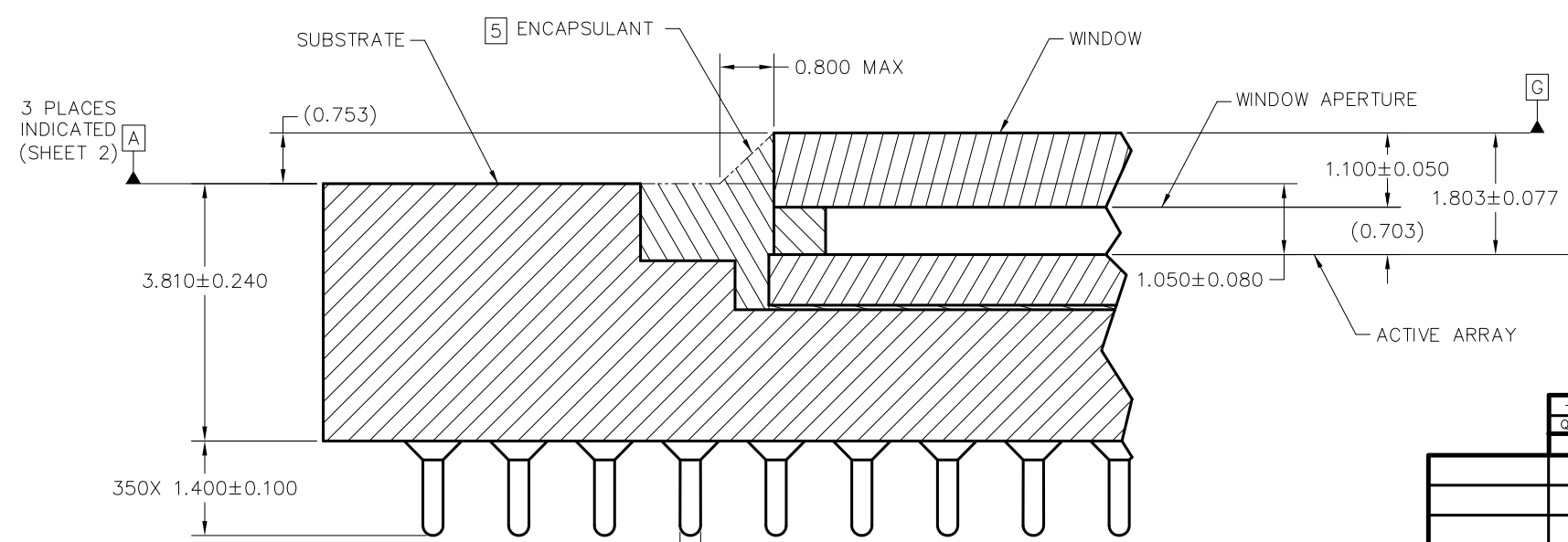
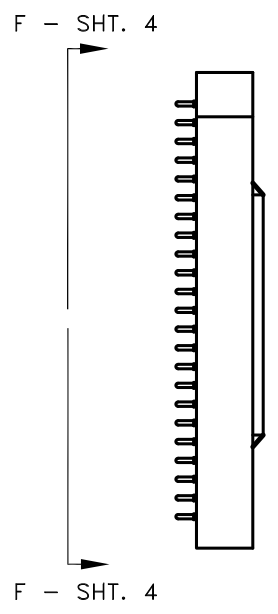
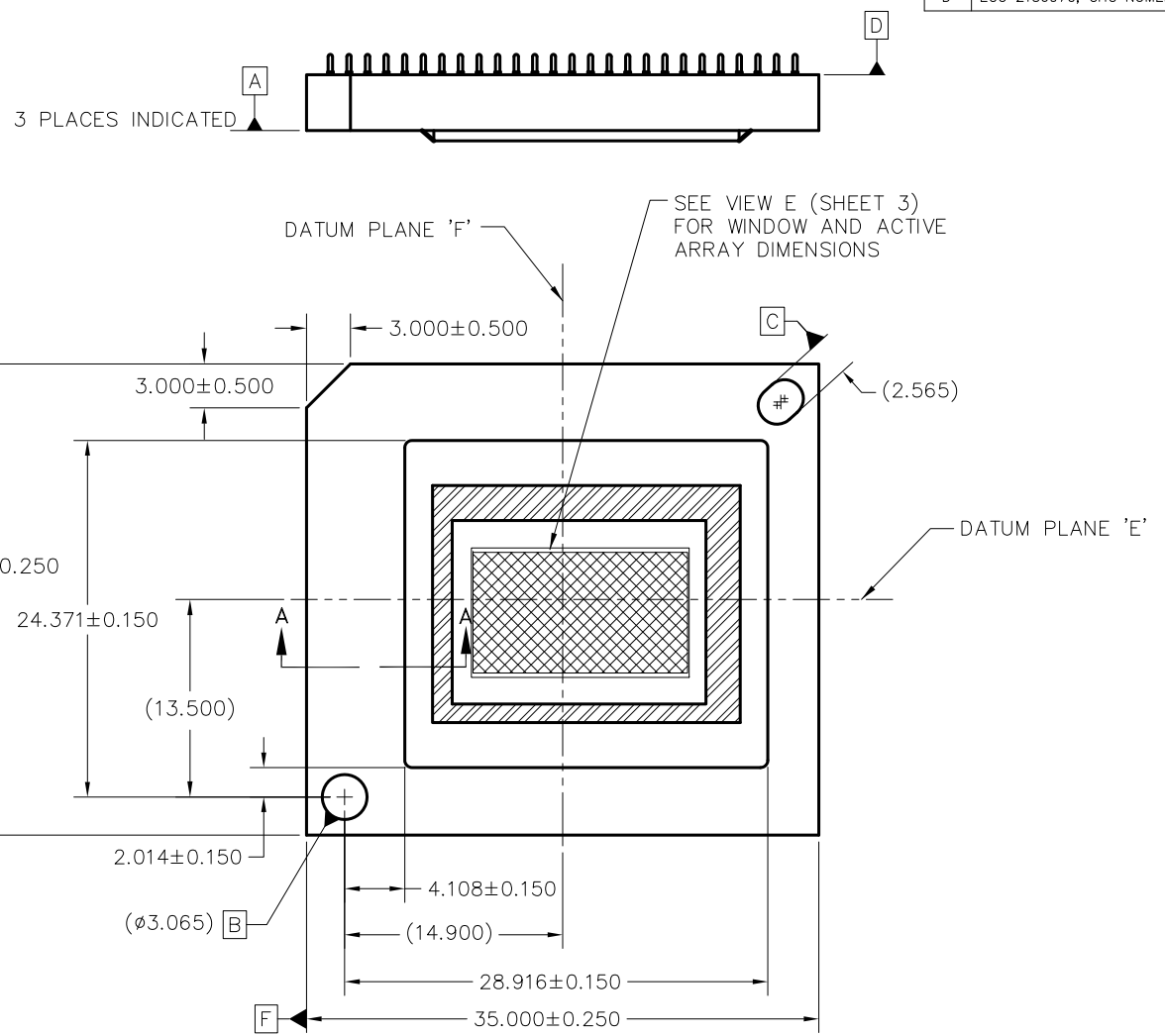


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	ECO 2146754, INITIAL RELEASE	11/18/2014	M. AVERY
B	ECO 2147303, ADD GLASS DIMS	12/18/2014	F. ARMSTRONG
C	ECO 2149265, CHG ARRAY TO 1528 ROWS	03/17/2015	F. ARMSTRONG
D	ECO 2156970, CHG NUMERICAL IDENTIFIER TO 317	03/17/2016	F. ARMSTRONG

NOTES: UNLESS OTHERWISE SPECIFIED:

- 1 DIE PARALLELISM TOLERANCE APPLIES TO DMD ACTIVE ARRAY ONLY
- 2 ROTATION ANGLE OF DMD ACTIVE ARRAY IS A REFINEMENT OF THE LOCATION TOLERANCE AND HAS A MAXIMUM ALLOWED VALUE OF 0.8 DEGREES
- 3 SUBSTRATE SYMBOLIZATION PAD AND PLATING AT BOTTOM OF DATUMS B AND C HOLES ARE ELECTRICALLY CONNECTED TO VSS PLANE WITHIN THE SUBSTRATE
- 4 BOUNDARY MIRRORS SURROUNDING THE DMD ACTIVE AREA
- 5 MAXIMUM ENCAPSULANT PROFILE SHOWN
- 6 ENCAPSULANT ALLOWED ON THE SURFACE OF THE CERAMIC IN THE AREA SHOWN IN VIEW B (SHEET 2). ENCAPSULANT SHALL NOT EXCEED 0.200 THICKNESS MAXIMUM.
- 7 SUBSTRATES PLATED WITH Ni/Au SHALL HAVE THE THREE-DIGIT NUMERICAL MARKING IN THE AREA ABOVE THE SYMBOLIZATION PAD. SUBSTRATES PLATED WITH Ni/Pd/Au SHALL HAVE THE MARKING IN THE AREA BELOW THE SYMBOLIZATION PAD.

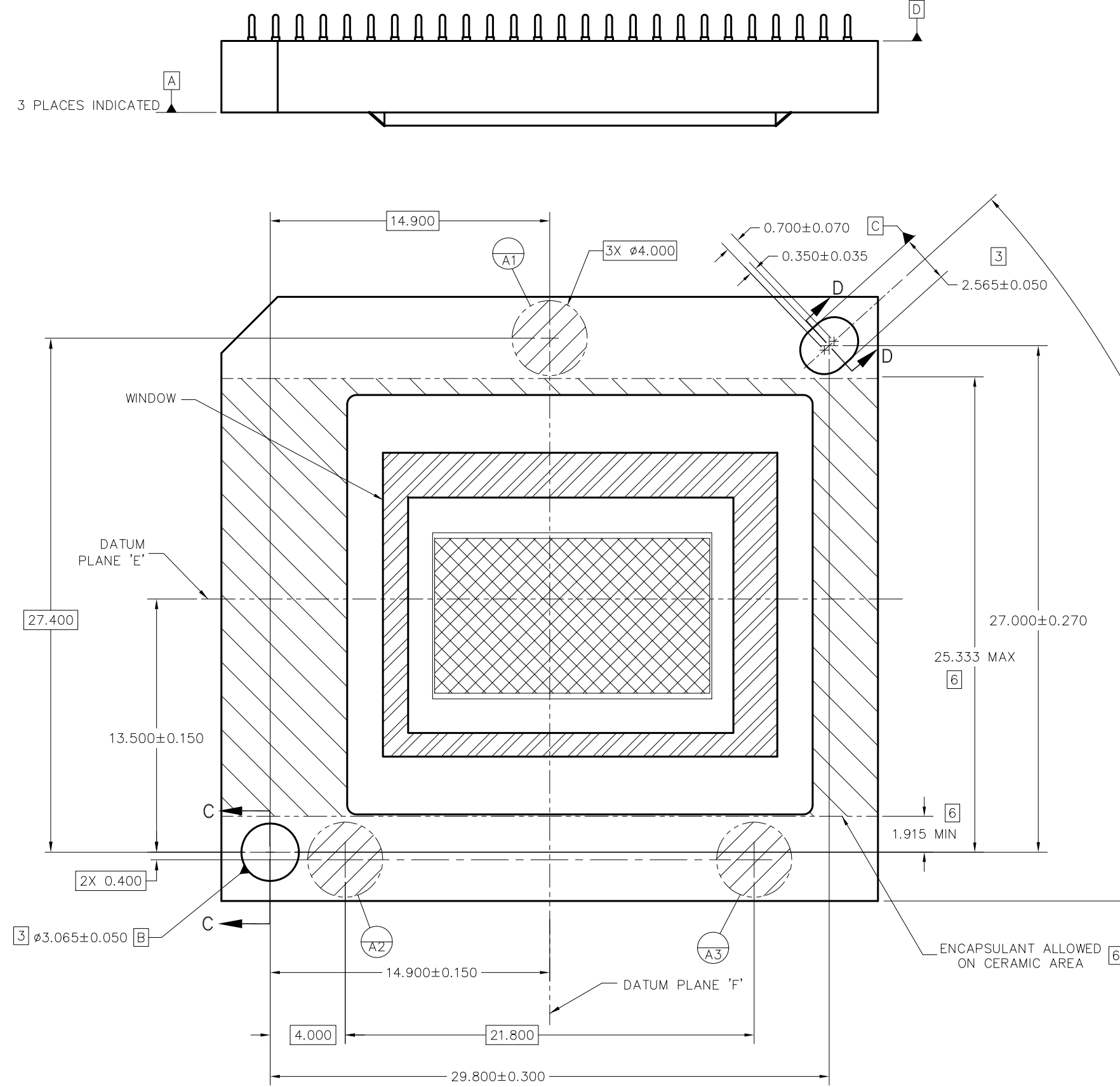


SECTION A-A
SCALE 20/1

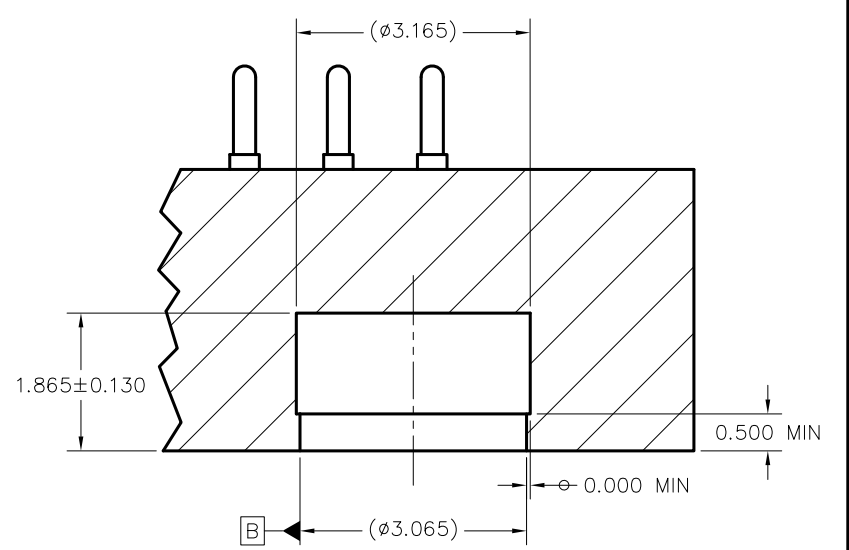
QTY	ITEM NO	PART OR IDENTIFYING NUMBER	NOMENCLATURE OR DESCRIPTION	NOTES
-1				

PARTS LIST		DATE	
DWN	M. AVERY	11/18/2014	
ENGR	F. ARMSTRONG	11/18/2014	
QA	P. KONRAD	12/04/2014	
PE	E. CARPENTER	12/04/2014	
COE	M. DORAK	12/04/2014	
	S. SUSI	12/04/2014	

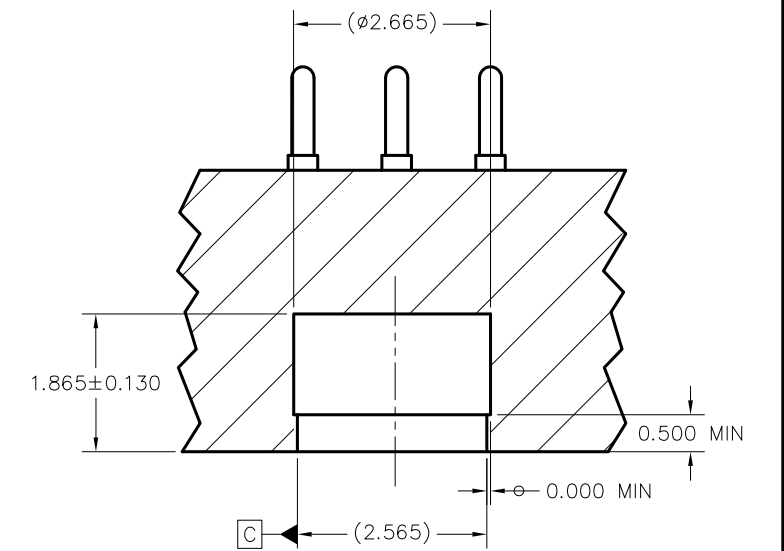
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES: ANGLES ± 1° 2 PLACE DECIMALS ±0.25 3 PLACE DECIMALS ±0.50		TEXAS INSTRUMENTS Dallas, Texas	
REMOVE ALL BURRS AND SHARP EDGES INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5-1994 DIMENSIONAL LIMITS APPLY BEFORE PROCESSES PARENTHEICAL INFO FOR REF ONLY		ICD, MECHANICAL, DMD .66 UHD HB MTRP 2XLVDS SERIES 610 (FYG PACKAGE)	
THIRD ANGLE PROJECTION	NONE	0314DA	SIZE D
NEXT ASSY	USED ON		DRAWING NO 2514366
APPLICATION			REV D



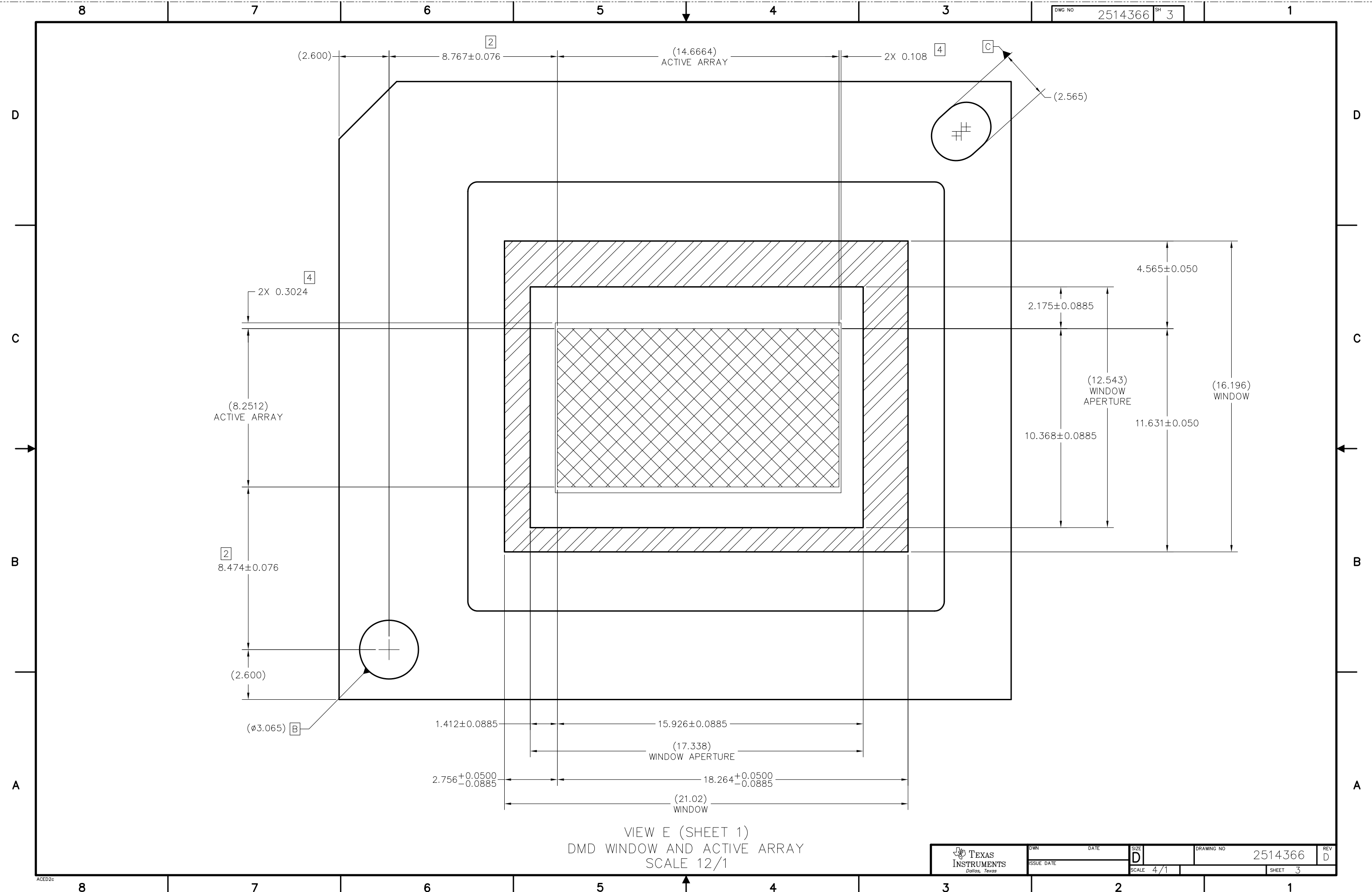
VIEW B
DATUMS AND ENCAPSULANT ALLOWABLE AREA
SCALE 8/1



SECTION C-C
DATUM B
SCALE 16/1



SECTION D-D
DATUM C
SCALE 16/1



VIEW E (SHEET 1)
 DMD WINDOW AND ACTIVE ARRAY
 SCALE 12/1

D

C

B

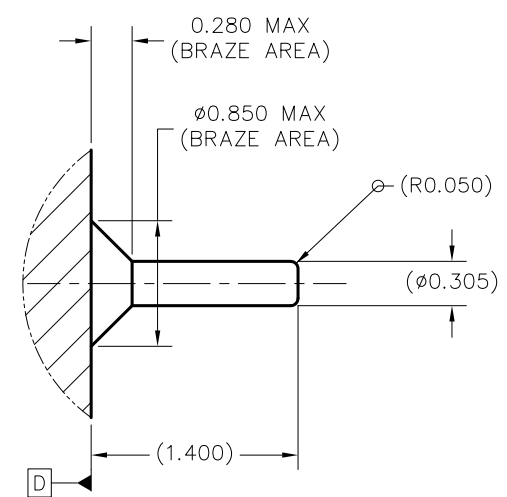
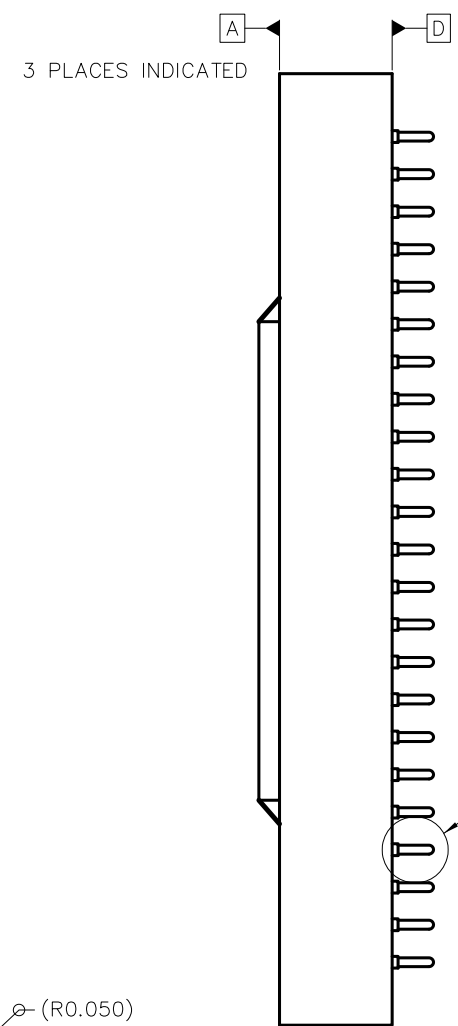
A

D

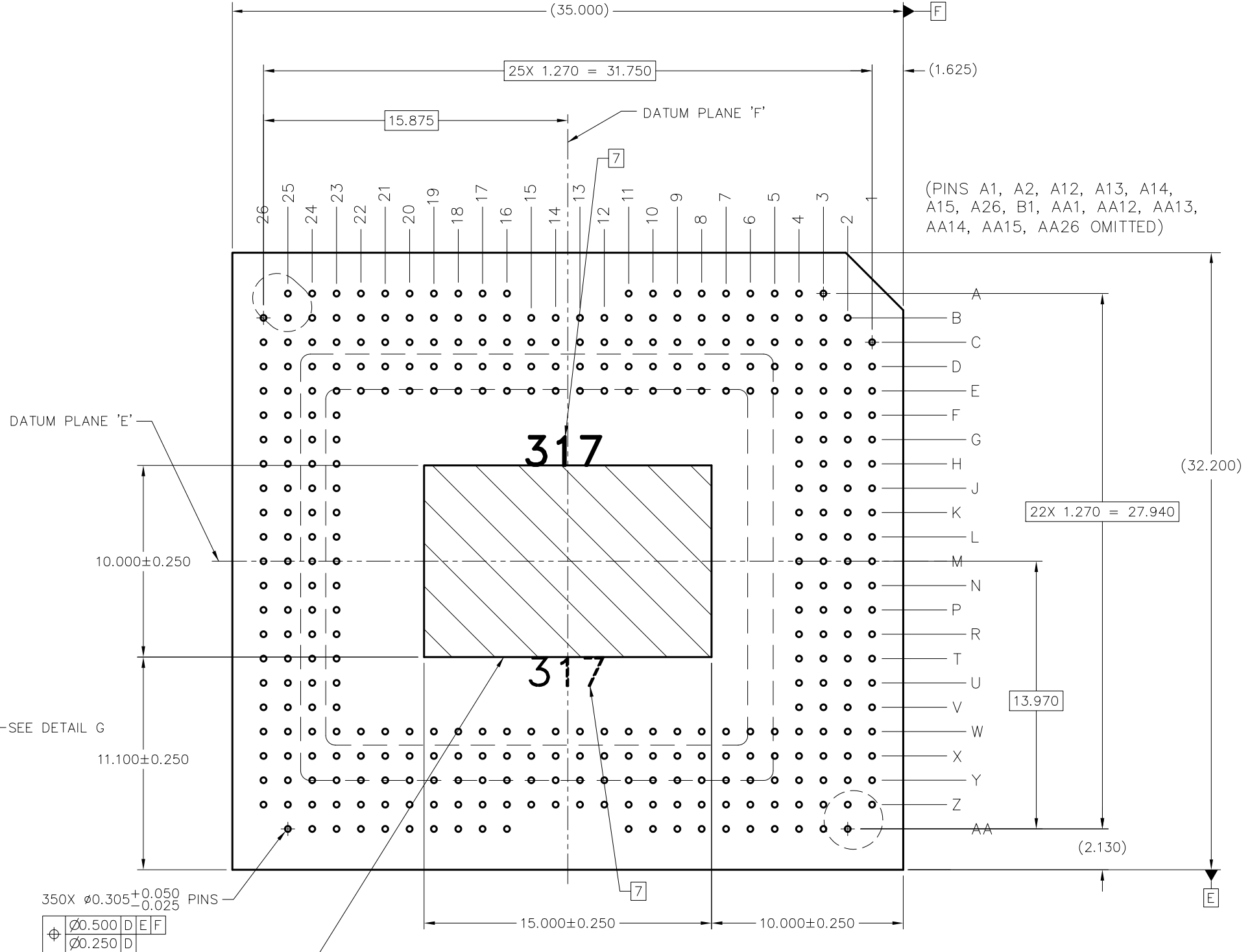
C

B

A



DETAIL G (350 PLACES)
PIN & BRAZE DIMENSIONS
SCALE 40/1



VIEW F-F (SHEET 1)
PINS AND SYMBOLIZATION PAD
SCALE 8/1

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